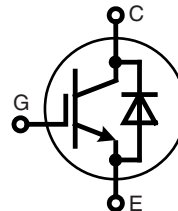
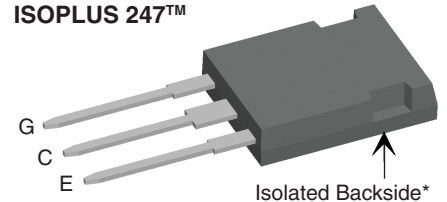


# High Voltage IGBT with optional Diode ISOPLUS™ package (Electrically Isolated Back Side)

$$\begin{aligned} V_{CES} &= 1200 \text{ V} \\ I_{C25} &= 50 \text{ A} \\ V_{CE(sat) \text{ typ}} &= 2.4 \text{ V} \end{aligned}$$

Short Circuit SOA Capability  
Square RBSOA


**ISOPLUS 247™**


G = Gate      C = Collector      E = Emitter

Symbol	Conditions	Maximum Ratings	
$V_{CES}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$	1200	V
$V_{CGR}$	$T_J = 25^\circ\text{C}$ to $150^\circ\text{C}$ ; $R_{GE} = 20 \text{ k}\Omega$	1200	V
$V_{GES}$	Continuous	$\pm 20$	V
$V_{GEM}$	Transient	$\pm 30$	V
$I_{C25}$	$T_C = 25^\circ\text{C}$	50	A
$I_{C90}$	$T_C = 90^\circ\text{C}$	30	A
$I_{CM}$	$T_C = 90^\circ\text{C}$ , $t_p = 1 \text{ ms}$	60	A
<b>RBSOA</b>	$V_{GE} = \pm 15 \text{ V}$ , $T_J = 125^\circ\text{C}$ , $R_G = 47 \Omega$ Clamped inductive load, $L = 30 \text{ mH}$	$I_{CM} = 50$ $V_{CEK} < V_{CES}$	A
$t_{SC}$ <b>(SCSOA)</b>	$V_{GE} = \pm 15 \text{ V}$ , $V_{CE} = V_{CES}$ , $T_J = 125^\circ\text{C}$ $R_G = 47 \Omega$ , non repetitive	10	$\mu\text{s}$
$P_c$	$T_C = 25^\circ\text{C}$	IGBT	200 W
		Diode	95 W
$T_J$		-55 ... +150	$^\circ\text{C}$
$T_{stg}$		-55 ... +150	$^\circ\text{C}$
$V_{ISOL}$	50/60 Hz, RMS $I_{ISOL} \leq 1 \text{ mA}$	2500	V~
<b>Weight</b>		6	g

**Features**

- NPT IGBT technology
  - high switching speed
  - low switching losses
  - square RBSOA, no latch up
  - high short circuit capability
  - positive temperature coefficient for easy paralleling
  - MOS input, voltage controlled
  - fast recovery epitaxial diode
- Epoxy meets UL 94V-0
- Isolated and UL registered E153432

**Advantages**

- DCB Isolated mounting tab meets TO-247AD package outline
- Package for clip or spring mounting
- Space savings
- High power density

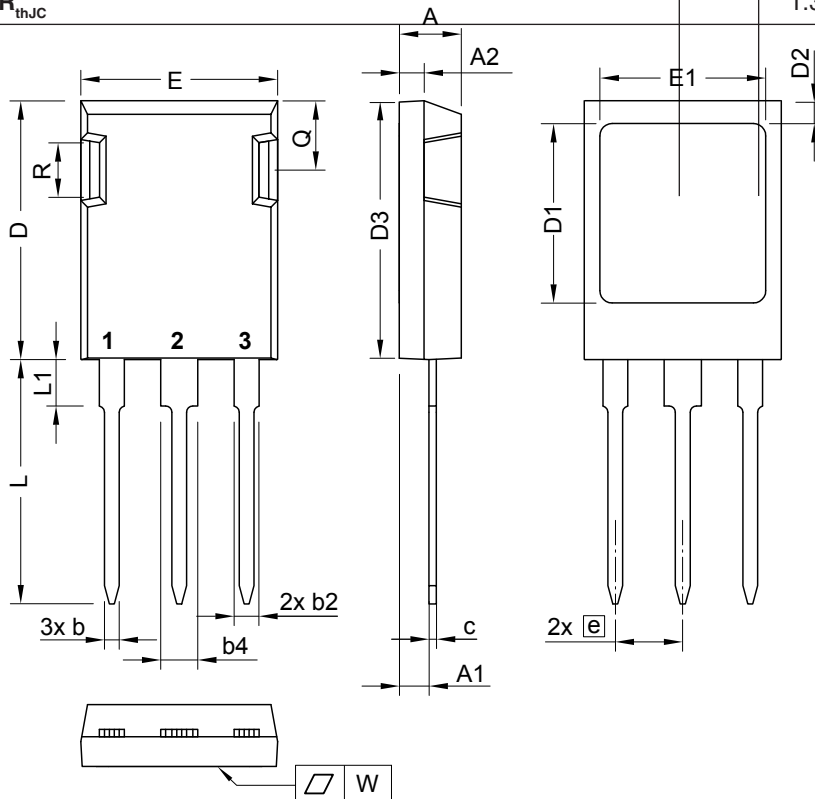
**Typical Applications**

- AC motor speed control
- DC servo and robot drives
- DC choppers
- Uninterruptible power supplies (UPS)
- Switch-mode and resonant-mode power supplies

Symbol	Conditions	Characteristic Values ( $T_J = 25^\circ\text{C}$ , unless otherwise specified)		
		min.	typ.	max.
$V_{(BR)CES}$	$V_{GE} = 0 \text{ V}$	1200		V
$V_{GE(th)}$	$I_C = 1 \text{ mA}$ , $V_{CE} = V_{GE}$	4.5		V
$I_{CES}$	$V_{CE} = V_{CES}$ , $T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$			1.5 mA
			2.5	mA
$I_{GES}$	$V_{CE} = 0 \text{ V}$ , $V_{GE} = \pm 20 \text{ V}$			$\pm 500 \text{ nA}$
$V_{CE(sat)}$	$I_C = 30 \text{ A}$ , $V_{GE} = 15 \text{ V}$	2.4	2.9	V

Symbol	Conditions	Characteristic Values		
		$(T_J = 25^\circ\text{C}, \text{ unless otherwise specified})$		
		min.	typ.	max.
$C_{ies}$	$V_{CE} = 25\text{ V}, V_{GE} = 0\text{ V}, f = 1\text{ MHz}$		1650	pF
$C_{oes}$			250	pF
$C_{res}$			110	pF
$Q_g$	$I_C = 30\text{ A}, V_{GE} = 15\text{ V}, V_{CE} = 0.5 V_{CES}$		120	nC
$t_{d(on)}$	Inductive load, $T_J = 125^\circ\text{C}$ $I_C = 30\text{ A}, V_{GE} = \pm 15\text{ V},$ $V_{CE} = 600\text{ V}, R_G = 47\ \Omega$		100	ns
$t_r$			70	ns
$t_{d(off)}$			500	ns
$t_f$			70	ns
$E_{on}$			4.6	mJ
$E_{off}$			3.4	mJ
$R_{thJC}$				0.6 K/W
$R_{thCH}$	Package with heatsink compound		0.25	K/W

Symbol	Conditions	Characteristic Values		
		$(T_J = 25^\circ\text{C}, \text{ unless otherwise specified})$		
		min.	typ.	max.
$V_F$	$I_F = 30\text{ A}, V_{GE} = 0\text{ V}$		2.5	2.75 V
	$I_F = 30\text{ A}, V_{GE} = 0\text{ V}, T_J = 125^\circ\text{C}$		2.0	V
$I_F$	$T_C = 25^\circ\text{C}$			50 A
	$T_C = 90^\circ\text{C}$			27 A
$I_{RM}$	$I_F = 30\text{ A}, -di_F/dt = 400\text{ A}/\mu\text{s}, V_R = 600\text{ V}$		20	A
$t_{rr}$	$V_{GE} = 0\text{ V}, T_J = 125^\circ\text{C}$		200	ns
$t_{rr}$	$I_F = 1\text{ A}, -di_F/dt = 100\text{ A}/\mu\text{s}, V_R = 30\text{ V}, V_{GE} = 0\text{ V}$		40	ns
$R_{thJC}$				1.3 K/W



Dim.	Millimeter		Inches	
	min	max	min	max
A	4.83	5.21	0.190	0.205
A1	2.29	2.54	0.090	0.100
A2	1.91	2.16	0.075	0.085
b	1.14	1.40	0.045	0.055
b2	1.91	2.20	0.075	0.087
b4	2.92	3.24	0.115	0.128
c	0.61	0.83	0.024	0.033
D	20.80	21.34	0.819	0.840
D1	15.75	16.26	0.620	0.640
D2	1.65	2.15	0.065	0.085
D3	20.30	20.70	0.799	0.815
E	15.75	16.13	0.620	0.635
E1	13.21	13.72	0.520	0.540
e	5.45 BSC		0.215 BSC	
L	19.81	20.60	0.780	0.811
L1	3.81	4.38	0.150	0.172
Q	5.59	6.20	0.220	0.244
R	4.25	5.50	0.167	0.217
W	-	0.10	-	0.004

Die konvexe Form des Substrates ist typ. < 0.04 mm über der Kunststoffoberfläche der Bauteilunterseite  
The convex bow of substrate is typ. < 0.04 mm over plastic surface level of device bottom side

Die Gehäuseabmessungen entsprechen dem Typ TO-247 AD gemäß JEDEC außer Schraubloch und  $L_{max}$ .  
This drawing will meet all dimensions requirement of JEDEC outline TO-247 AD except screw hole and except  $L_{max}$ .

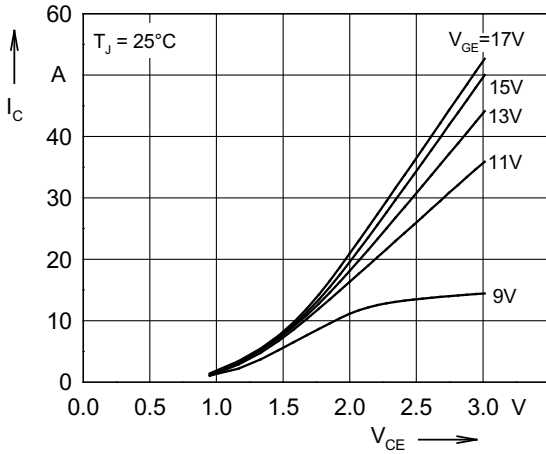


Fig. 1 Typ. output characteristics

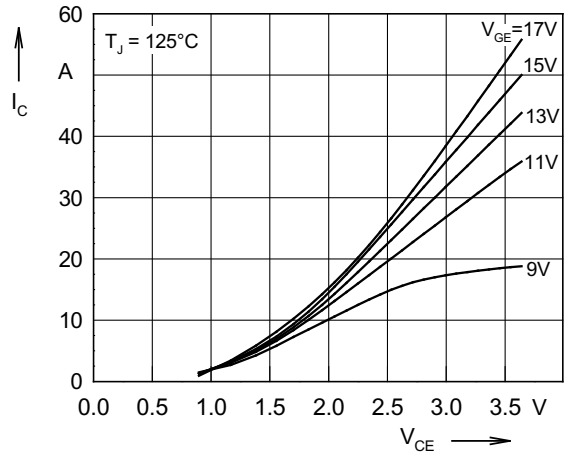


Fig. 2 Typ. output characteristics

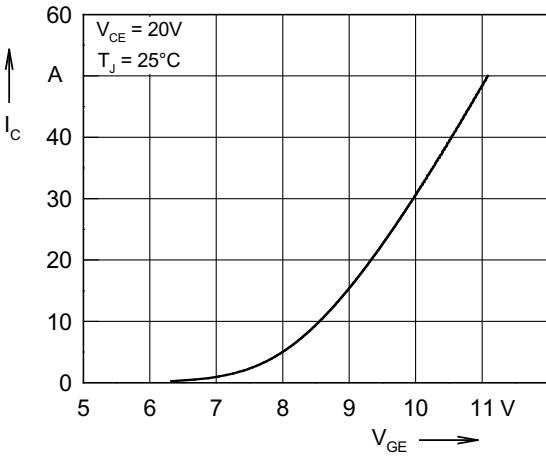


Fig. 3 Typ. transfer characteristics

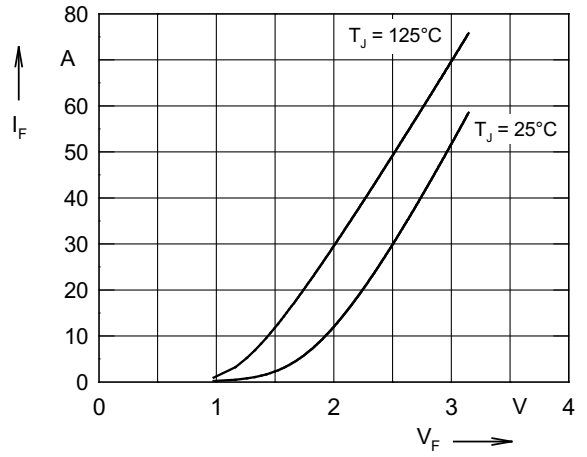


Fig. 4 Typ. forward characteristics of free wheeling diode

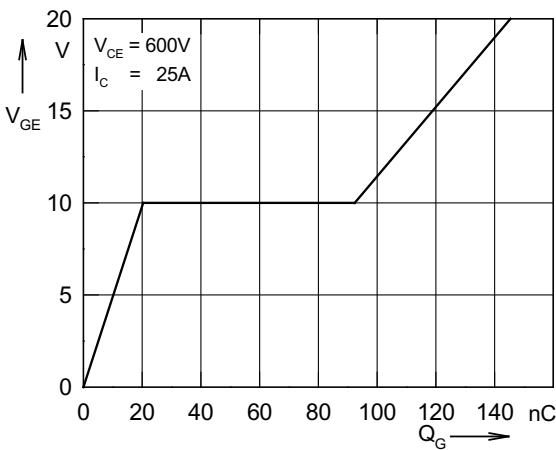


Fig. 5 Typ. turn on gate charge

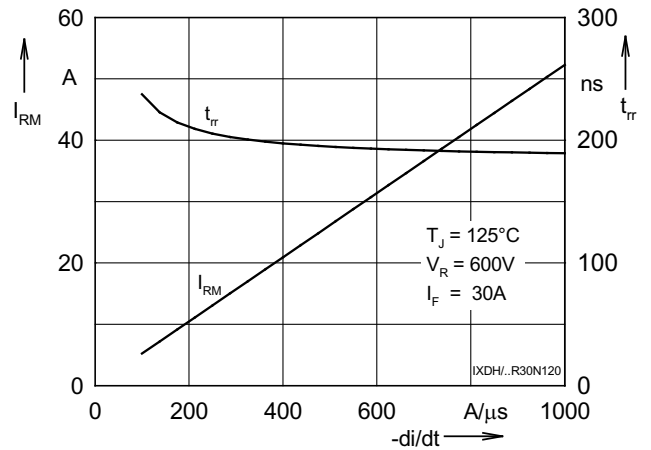


Fig. 6 Typ. turn off characteristics of free wheeling diode